## **REMARKS**

This is intended as a full and complete response to the Notice to File Corrected Application Papers dated May 24, 2004, having a shortened statutory period for response extended one month to expire on August 24, 2004. Please reconsider the drawings in the application and the amendments in the specification for the reasons presented below.

The drawings have been amended and replacement sheets are attached in compliance with 37 CFR 1.84 and 37 CFR 1.121 as required. Applicants respectfully request entry of the corrected drawings and submit that no new matter has been included.

The specification has been amended to reflect the changes in the drawings and to correct minor editorial errors. Applicants respectfully request entry of these amendments prior to examination and assert that no new matter has been added.

The pending claims are attached and have been amended to correct minor typographical errors. Applicants respectfully request that the amendments be entered before examination.

Having addressed all issues set out in the Notice to File Corrected Application Papers, Applicants respectfully submit that the application is in condition for allowance and respectfully request that the pending claims be allowed.

Respectfully submitted,

Keith M. Tackett

Registration No. 32,008

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Telephone: (713) 623-4844 Facsimile: (713) 623-4846 Attorney for Applicant(s) ATTY DKT. NO.: U.S. SERIAL NO.:

FILED: APPLICANT: TITLE:

AMAT/5614.D1/CMP/CMP/RKK 10/792,069 MARCH 3, 2004 APPLIED MATERIALS, INC.

INTEGRATED MULTI-STEP GAP FILL AND FEATURE PLANARIZATION FOR CONDUCTIVE MATERIALS

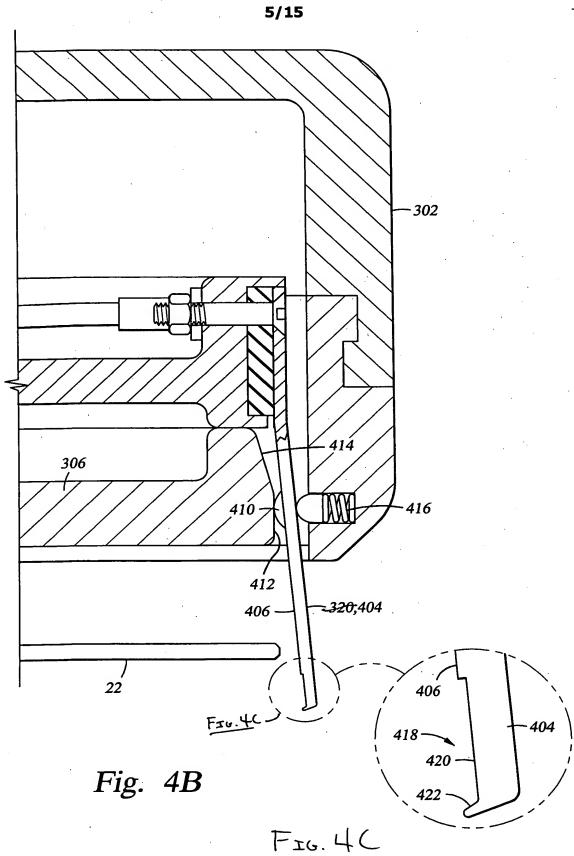
INVENTOR:

HSU, ET AL.

ANNOTATED SHEETS

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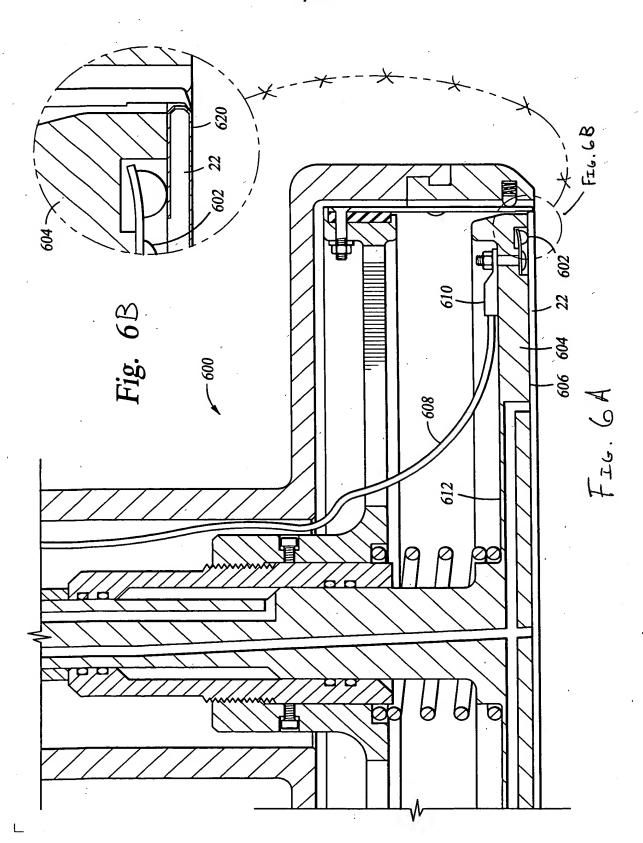
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INTEGRATED MULTI-STEP GAP FILL AND FEATURE
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HSU, ET AL.
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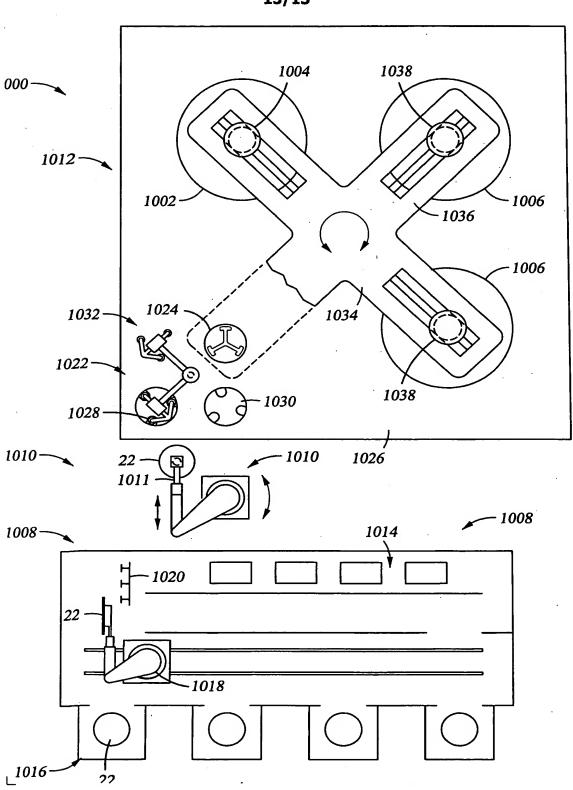


FIG. 10